

IN THE SPECIFICATION

Please replace the paragraph at page 13, lines 31-33, with the following rewritten paragraph:

More preferably, the heat exchange means reduces a temperature of the focus ring to at least  $[[20K]]$   $20^{\circ}\text{C}$  below a temperature of the electrostatic chuck.

Please replace the paragraph at page 13, line 34 to page 14, line 2, with the following rewritten paragraph:

According to this preferred form, the temperature of the focus ring is reduced to at least  $[[20K]]$   $20^{\circ}\text{C}$  below the temperature of the electrostatic chuck. As a result, the deposit can be attached to the focus ring reliably.

Please replace the paragraph at page 47, line 25 to page 48, line 1, with the following rewritten paragraph:

When cooling the focus ring 30, it is preferable to reduce the temperature of the focus ring 30 to at least  $[[20K]]$   $20^{\circ}\text{C}$  below the temperature of the electrostatic chuck 25. Even during the dry etching processing, the temperature of the electrostatic chuck 25 is maintained at approximately  $20^{\circ}\text{C}$  by the coolant chamber 31 inside the lower electrode 11. Upon reducing the temperature of the focus ring 30 to at least  $[[20K]]$   $20^{\circ}\text{C}$  below the temperature of the electrostatic chuck 25, the temperature of the focus ring 30 will thus be reduced to not more than  $0^{\circ}\text{C}$ . As a result, depositable radicals can be reliably attached to the focus ring 30.